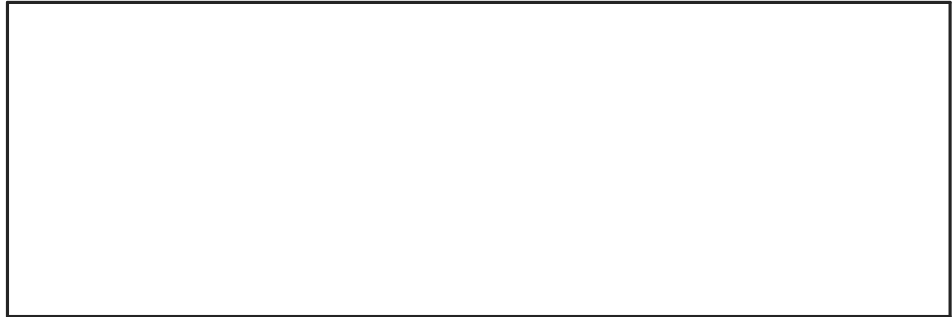


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: PMP20744	REV: PMP9074_RSVD REV: Not In VersionControl
IGNORE ->		
PLOT NAME = Top Assembly Drawing	GENERATED : 2/24/2017 4:03:02 PM	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP20744	REV: PMP9074_RSVD	REV: Not In VersionControl
	IGNORE ->		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 2/24/2017 4:03:04 PM	TEXAS INSTRUMENTS	

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